I hereby certify that this correspondence is being deposited with the United States Postal Service on the date set forth below as First Class Mail in an envelope addressed to: Box Amendment, Commissioner for Patents, Washington, D. C. 20231. Date of Signature and Deposit: November 14, 2002

ee ok

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Serial No .:

Richard D. Harris, et. al. 09/967,157/

Filed:

For:

September 28, 2001

Method for fabricating a microelectromechanical system (MEMS)

Group Art Unit:

Docket No.:

110003.97630

		<u>-:</u> :		
	AMENDMENT	- 23		70
Box Amendment Commissioner for Patents Washington, D. C. 20231		THEO ABOT	101/22 20	ECEIVE
Dear Sir:		EN 2	£3	
In response to the Office Act		800		•

In response to the Office Action dated August 14, 2002, please amend the aboveidentified patent application as follows: IN THE CLAIMS:

The following revised claims should be substituted for the like numbered claims that were filed with the patent Application. Claims 15, 24, 33, 49, and 50 should be cancelled from the application. New claims 53-102 should be added to the application. A version of the claims with markings to show changes made is attached to the end of this

1. (Once Amended) A method of fabricating a MEMS structure, comprising the steps of: (a)

- providing a wafer having at least a first layer and a second layer;
- removing a portion of the first layer through to the second layer to (b) (c)
- after step (b), attaching the wafer to the upper surface of a substrate

to form a composite structure having an internal void formed therein, wherein the 11/21/2002 DTESSEM1 00000046 170055 09967157 01 FC:1202 02 FC:1201 810.00 CH 420.00 CH